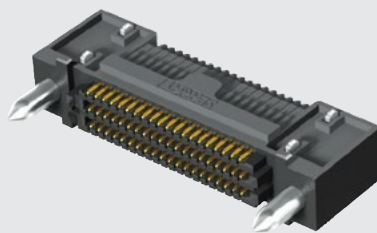
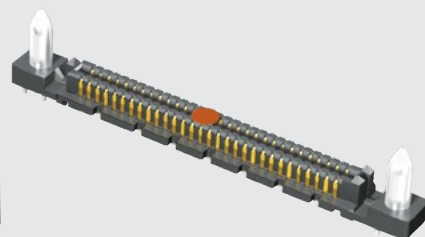



SEARAY™


SEAM-20-01-L-06-2-RA-GP-TR



SEAM-30-02.0-L-04-2-A-GP-K-TR

(1.27 mm) .050"

SEAM-RA, SEAM-GP SERIES

HI-DENSITY RIGHT-ANGLE OPEN-PIN-FIELD

SEAM-RA Mates with:
SEAF, SEAF-RA, SEAFP

SEAM-GP Mates with:
SEAF-RA-GP

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SEAM-RA or www.samtec.com?SEAM

Insulator Material:
Black LCP

Contact Material:
Copper Alloy

Current Rating:
SEAM-RA = 1.9 A per pin
(10 pins powered)

Operating Temp Range:
-55 °C to +125 °C

Plating:
Au or Sn over
50 μ" (1.27 μm) Ni

Working Voltage:
SEAM-RA = 260 VAC
SEAM-GP = 240 VAC

Mated Cycles:
SEAM-GP = 100

RoHS Compliant:
Yes

Lead-Free Solderable:
Yes

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594

Notes:
SEAM-GP Patented

Some sizes, styles and options are non-standard, non-returnable.

SEAM	NO. PINS PER ROW	01	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	RA	OPTION	"X"R
	-20, -30, -40, -50		-L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail -S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on solder tail	-04 = Four Rows -06 = Six Rows -08* = Eight Rows -10* = Ten Rows	-1 = Tin/Lead Alloy Solder Charge -2 = Lead-Free Solder Charge		-GP = Guide Post -K = Polyimide film Pick & Place Pad	-TR = Tape & Reel -FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)

HIGH-SPEED CHANNEL PERFORMANCE

SEAM-RA/SEAF-RA
Rating based on Samtec reference channel.
For full SI performance data visit www.samtec.com or contact SIG@samtec.com

NO. PINS PER ROW	A
-20	(38.94) 1.533
-30	(51.64) 2.033
-40	(64.34) 2.533
-50	(77.04) 3.03

25 Gbps

Diagram Dimensions:
 (8.13) .320 (19.30) .760 (12.32) .485 (7.91) .312 (1.60) .063 (0.64) .025
 -GP= No. of positions x (1.27) .050 + (19.56) 0.77
 Without -GP= No. of positions x (1.27) .050 + (11.18) 0.44
 A
 (5.36) .211 (3.05) .120 DIA (1.27) .050

Wipe Detail:
(1.12 mm) .044" NOMINAL WIPE

SEAM	NO. PINS PER ROW	02.0	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	A	GP	K	"X"R
	-20, -30, -40, -50		-L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail -S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on solder tail	-04 = Four Rows -06 = Six Rows -08 = Eight Rows -10 = Ten Rows	-1 = Tin/Lead Alloy Solder Charge -2 = Lead-Free Solder Charge			-K = Polyimide film Pick & Place Pad -TR = Tape & Reel (Not available with 50 positions) -FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks) (Not available with 50 positions)	

Diagram Dimensions:
 (5.54) .218 (06) (01)
 No. of positions x (1.27) .050 + (19.46) .766
 (3.05) .120 DIA (1.27) .050 (1.27) .050 (1.12) .044 DIA (0.86) .034 DIA (0.51) .020 SQ (1.02) .040 (8.13) .320 (12.65) .498 (4.60) .181 (1.27) .050

ALSO AVAILABLE (MOQ Required)

- Extended Guide Post
- Guide post field termination kits
- Other platings

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications.
Components must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.